

SOT1041-1

plastic flip chip strap package; 2 leads; 12 mm wide tape

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	FCS2
Package type industry code	FCS2
Package style descriptive code	FCS (flip chip strap)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-10-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.7	-	12	12.3	mm
A	seated height		[tbd]	-	0.25	0.25	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

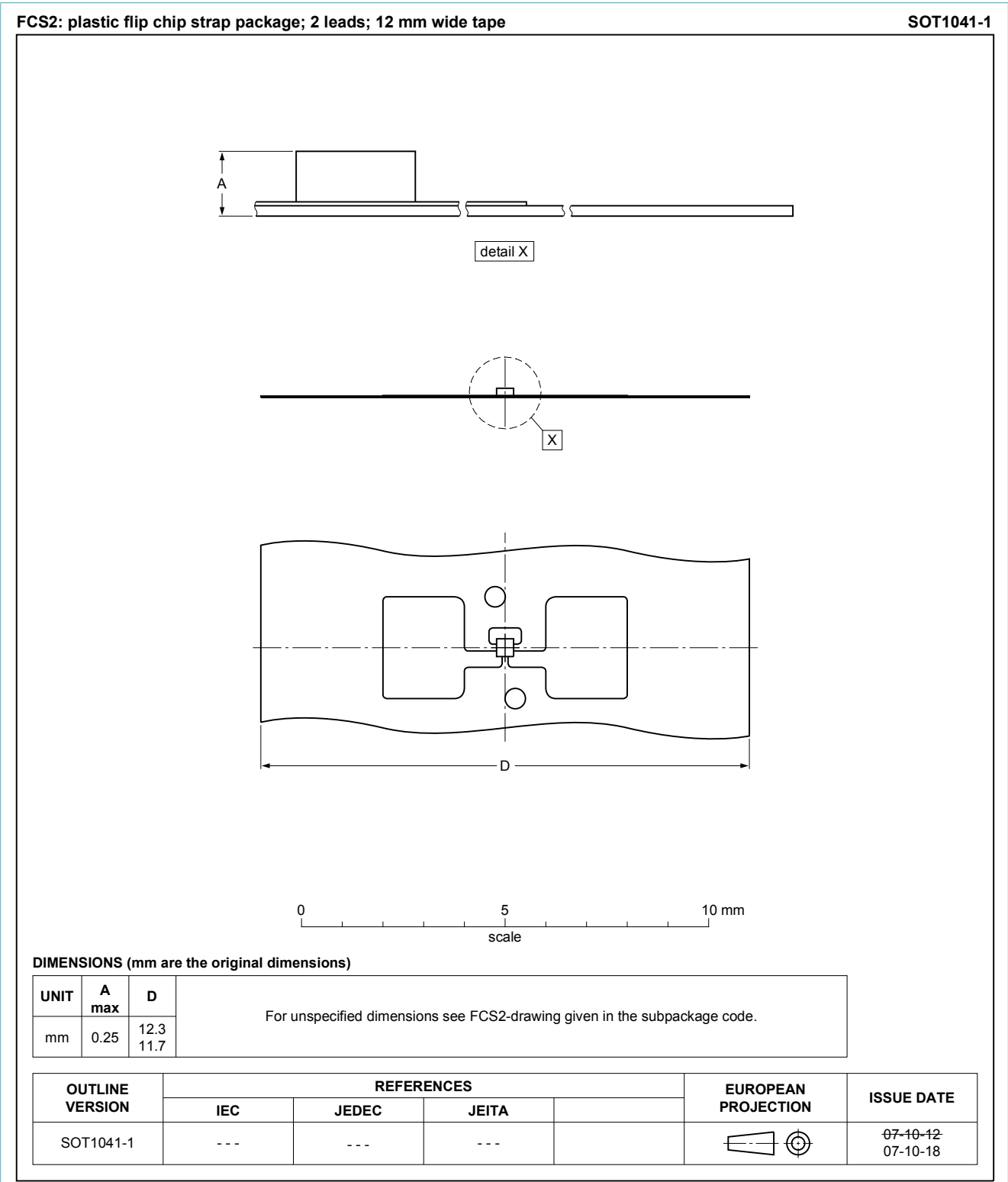


Fig. 1. Package outline FCS2 (SOT1041-1)

3. Legal information

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